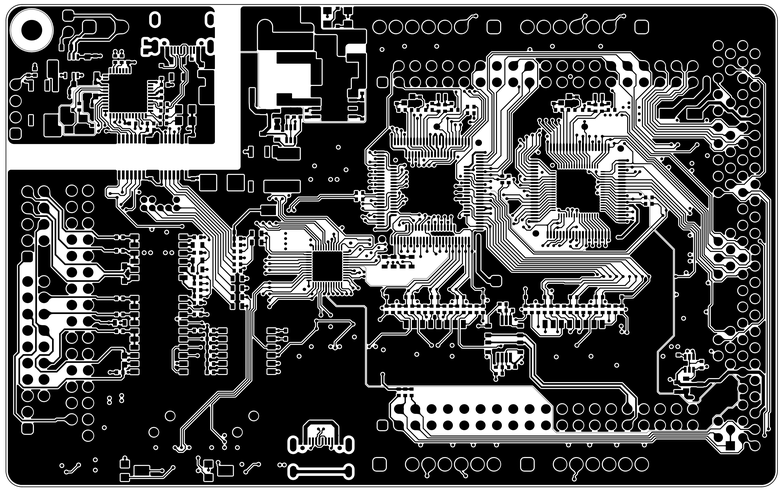
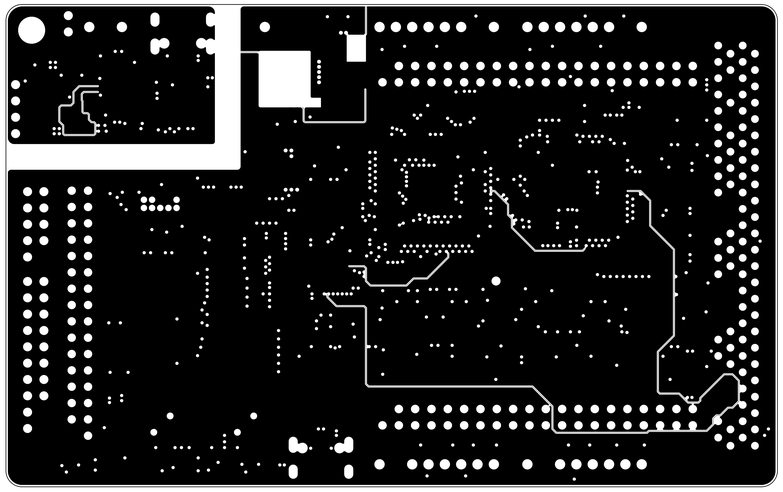


Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Lack	0,030mm	3.8	
	Top Surface Finish	Nickel, Gold	0,004mm		
1	L1_TOP_SIG	CF-004	0,035mm		
	Dielectric 1	PP-016	0,117mm	4.16	
2	L2_INT1_GND	CF-003	0,018mm		
	Core 1	Core-029	0,305mm	4.6	
3	L3_INT2_SIG	CF-003	0,018mm		
	Dielectric 2	PP-007	0,076mm	3.91	
	Dielectric 3	PP-007	0,076mm	3.91	
4	L4_INT3_PWR	CF-003	0,018mm		
	Core 2	Core-029	0,305mm	4.6	
5	L5_INT4_PWR	CF-003	0,018mm		
	Dielectric 4	PP-007	0,076mm	3.91	
	Dielectric 5	PP-007	0,076mm	3.91	
6	L6_INT5_SIG	CF-003	0,018mm		
	Core 3	Core-029	0,305mm	4.6	
7	L7_INT6_GND	CF-003	0,018mm		
	Dielectric 6	PP-016	0,117mm	4.16	
8	L8_BOT_SIG	CF-004	0,035mm		
	Bottom Surface Finish	Nickel, Gold	0,004mm		
	Bottom Solder	Lack	0,030mm	3.8	
	Bottom Overlay				

Infineon Technologies AG
IFAG CSS ICW MCU APP IND
Am Campeon 1-12
85579 NEUBIBERG – GERMANY

ENGINEER:	TITLE: KIT_PSC3Mx_CC2		
PCB DESIGNER: M.N.			
DATE: 28.08.2026	PART NO.:	REL: 1.0	REV:
SVN REVISION: Not in version control	FILE NAME: KIT_PSC3Mx_CC2.PcbDoc	APRV: <Appr.>	SCALE: 1:1

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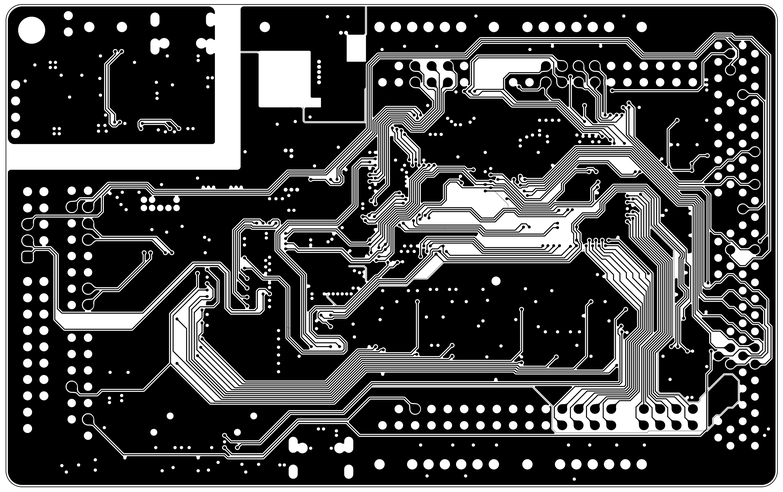


Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
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	Dielectric 4	PP-007	0,076mm	3.91	
	Dielectric 5	PP-007	0,076mm	3.91	
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	Core 3	Core-029	0,305mm	4.6	
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	Dielectric 6	PP-016	0,117mm	4.16	
8	L8_BOT_SIG	CF-004	0,035mm		
	Bottom Surface Finish	Nickel, Gold	0,004mm		
	Bottom Solder	Lack	0,030mm	3.8	
	Bottom Overlay				

Infineon Technologies AG
IFAG CSS ICW MCU APP IND
Am Campeon 1-12
85579 NEUBIBERG – GERMANY

ENGINEER:		TITLE: KIT_PSC3Mx_CC2	
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DATE: 28.08.2026	PART NO.:	REL: 1.0	REV:
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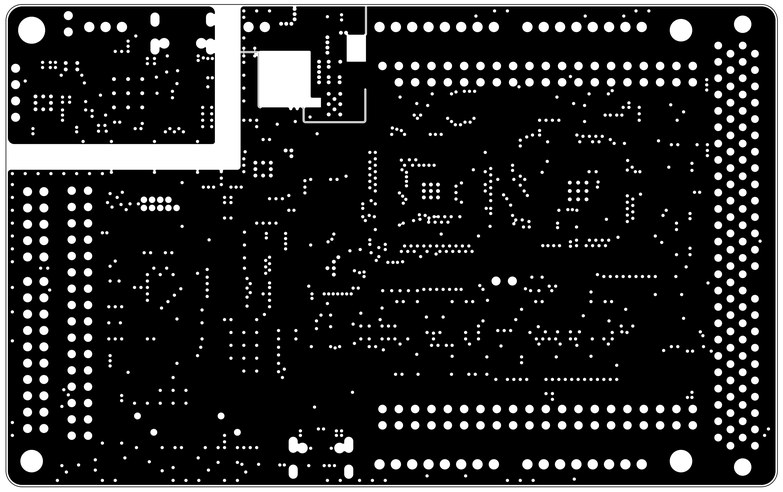


Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Lack	0,030mm	3.8	
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	Core 1	Core-029	0,305mm	4.6	
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	Dielectric 4	PP-007	0,076mm	3.91	
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	Dielectric 6	PP-016	0,117mm	4.16	
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	Bottom Surface Finish	Nickel, Gold	0,004mm		
	Bottom Solder	Lack	0,030mm	3.8	
	Bottom Overlay				

Infineon Technologies AG
IFAG CSS ICW MCU APP IND
Am Campeon 1-12
85579 NEUBIBERG – GERMANY

ENGINEER:	TITLE: KIT_PSC3Mx_CC2		
PCB DESIGNER: M.N.			
DATE: 28.08.2026	PART NO.:	REL: 1.0	REV:
SVN REVISION: Not in version control	FILE NAME: KIT_PSC3Mx_CC2.PcbDoc	APRV: <Appr.>	SCALE: 1:1

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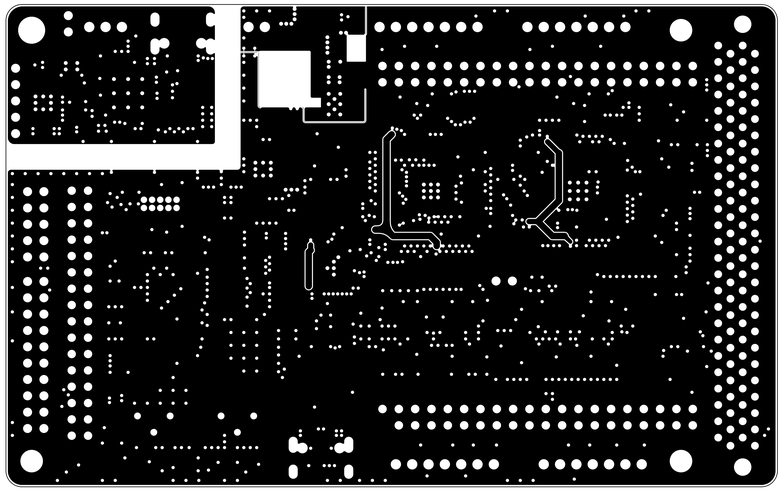


Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Lack	0,030mm	3.8	
	Top Surface Finish	Nickel, Gold	0,004mm		
1	L1_TOP_SIG	CF-004	0,035mm		
	Dielectric 1	PP-016	0,117mm	4.16	
2	L2_INT1_GND	CF-003	0,018mm		
	Core 1	Core-029	0,305mm	4.6	
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	Dielectric 2	PP-007	0,076mm	3.91	
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	Core 2	Core-029	0,305mm	4.6	
5	L5_INT4_PWR	CF-003	0,018mm		
	Dielectric 4	PP-007	0,076mm	3.91	
	Dielectric 5	PP-007	0,076mm	3.91	
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	Core 3	Core-029	0,305mm	4.6	
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	Dielectric 6	PP-016	0,117mm	4.16	
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	Bottom Surface Finish	Nickel, Gold	0,004mm		
	Bottom Solder	Lack	0,030mm	3.8	
	Bottom Overlay				

Infineon Technologies AG
IFAG CSS ICW MCU APP IND
Am Campeon 1-12
85579 NEUBIBERG - GERMANY

ENGINEER:	TITLE: KIT_PSC3Mx_CC2		
PCB DESIGNER: M.N.			
DATE: 28.08.2026	PART NO.:	REL: 1.0	REV:
SVN REVISION: Not in version control	FILE NAME: KIT_PSC3Mx_CC2.PcbDoc	APRV: <Appr.>	SCALE: 1:1

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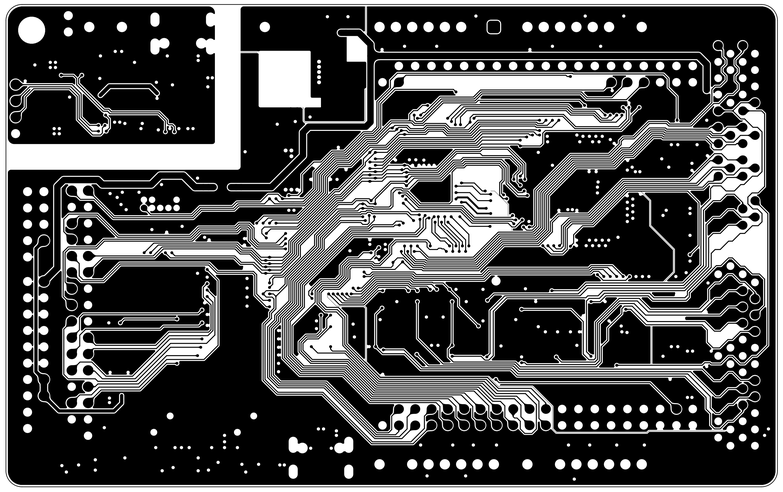


Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Lack	0,030mm	3.8	
	Top Surface Finish	Nickel, Gold	0,004mm		
1	L1_TOP_SIG	CF-004	0,035mm		
	Dielectric 1	PP-016	0,117mm	4.16	
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	Core 1	Core-029	0,305mm	4.6	
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	Dielectric 2	PP-007	0,076mm	3.91	
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	Dielectric 6	PP-016	0,117mm	4.16	
8	L8_BOT_SIG	CF-004	0,035mm		
	Bottom Surface Finish	Nickel, Gold	0,004mm		
	Bottom Solder	Lack	0,030mm	3.8	
	Bottom Overlay				

Infineon Technologies AG
IFAG CSS ICW MCU APP IND
Am Campeon 1-12
85579 NEUBIBERG – GERMANY

ENGINEER:	TITLE: KIT_PSC3Mx_CC2		
PCB DESIGNER: M.N.			
DATE: 28.08.2026	PART NO.:	REL: 1.0	REV:
SVN REVISION: Not in version control	FILE NAME: KIT_PSC3Mx_CC2.PcbDoc	APRV: <Appr.>	SCALE: 1:1

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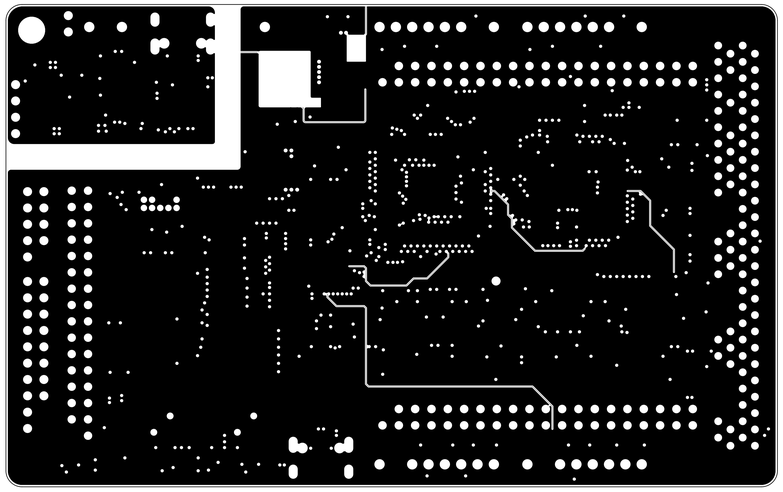


Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Lack	0,030mm	3.8	
	Top Surface Finish	Nickel, Gold	0,004mm		
1	L1_TOP_SIG	CF-004	0,035mm		
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	Core 1	Core-029	0,305mm	4.6	
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	Dielectric 2	PP-007	0,076mm	3.91	
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4	L4_INT3_PWR	CF-003	0,018mm		
	Core 2	Core-029	0,305mm	4.6	
5	L5_INT4_PWR	CF-003	0,018mm		
	Dielectric 4	PP-007	0,076mm	3.91	
	Dielectric 5	PP-007	0,076mm	3.91	
6	L6_INT5_SIG	CF-003	0,018mm		
	Core 3	Core-029	0,305mm	4.6	
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	Dielectric 6	PP-016	0,117mm	4.16	
8	L8_BOT_SIG	CF-004	0,035mm		
	Bottom Surface Finish	Nickel, Gold	0,004mm		
	Bottom Solder	Lack	0,030mm	3.8	
	Bottom Overlay				

Infineon Technologies AG
IFAG CSS ICW MCU APP IND
Am Campeon 1-12
85579 NEUBIBERG – GERMANY

ENGINEER:	TITLE: KIT_PSC3Mx_CC2		
PCB DESIGNER: M.N.			
DATE: 28.08.2026	PART NO.:	REL: 1.0	REV:
SVN REVISION: Not in version control	FILE NAME: KIT_PSC3Mx_CC2.PcbDoc	APRV: <Appr.>	SCALE: 1:1

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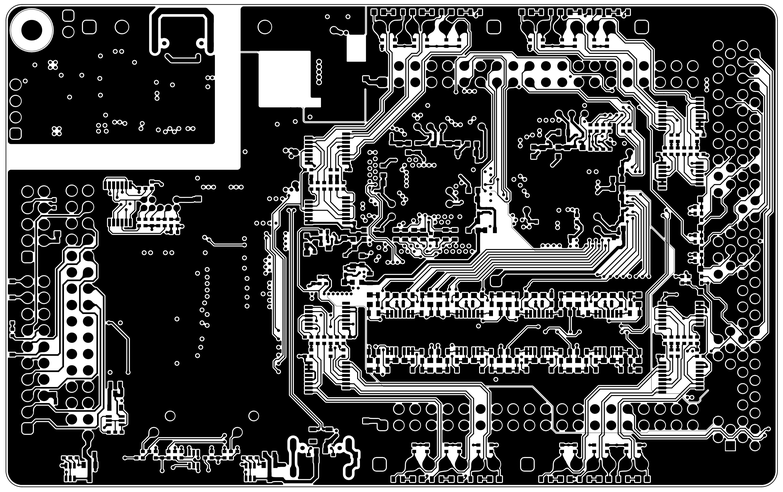


Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Lack	0,030mm	3.8	
	Top Surface Finish	Nickel, Gold	0,004mm		
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	Dielectric 1	PP-016	0,117mm	4.16	
2	L2_INT1_GND	CF-003	0,018mm		
	Core 1	Core-029	0,305mm	4.6	
3	L3_INT2_SIG	CF-003	0,018mm		
	Dielectric 2	PP-007	0,076mm	3.91	
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4	L4_INT3_PWR	CF-003	0,018mm		
	Core 2	Core-029	0,305mm	4.6	
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	Dielectric 4	PP-007	0,076mm	3.91	
	Dielectric 5	PP-007	0,076mm	3.91	
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	Core 3	Core-029	0,305mm	4.6	
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	Dielectric 6	PP-016	0,117mm	4.16	
8	L8_BOT_SIG	CF-004	0,035mm		
	Bottom Surface Finish	Nickel, Gold	0,004mm		
	Bottom Solder	Lack	0,030mm	3.8	
	Bottom Overlay				

Infineon Technologies AG
IFAG CSS ICW MCU APP IND
Am Campeon 1-12
85579 NEUBIBERG – GERMANY

ENGINEER:		TITLE: KIT_PSC3Mx_CC2	
PCB DESIGNER: M.N.			
DATE: 28.08.2026	PART NO.:	REL: 1.0	REV:
SVN REVISION: Not in version control	FILE NAME: KIT_PSC3Mx_CC2.PcbDoc	APRV: <Appr.>	SCALE: 1:1

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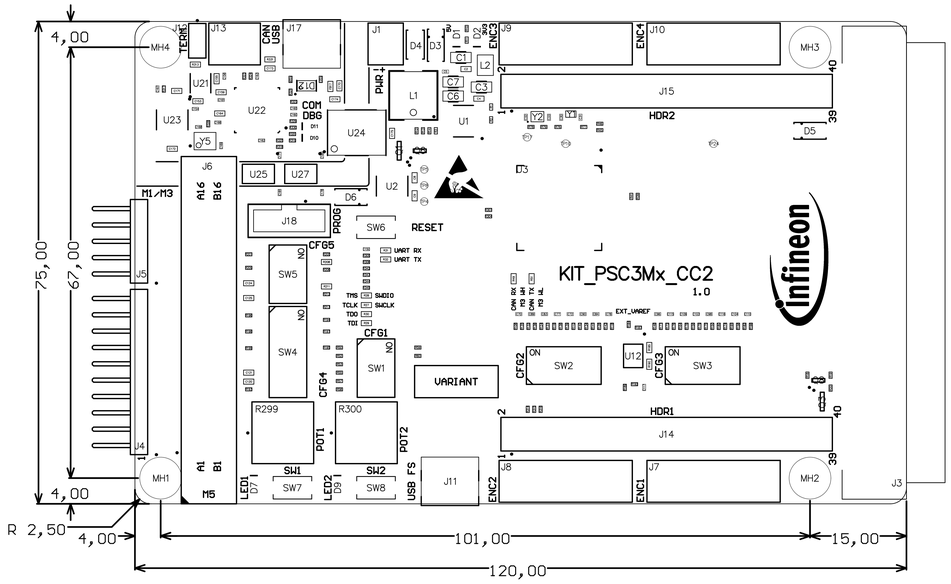


Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Lack	0,030mm	3.8	
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	Bottom Solder	Lack	0,030mm	3.8	
	Bottom Overlay				

Infineon Technologies AG
IFAG CSS ICW MCU APP IND
Am Campeon 1-12
85579 NEUBIBERG – GERMANY

ENGINEER:		TITLE: KIT_PSC3Mx_CC2	
PCB DESIGNER: M.N.			
DATE: 28.08.2026	PART NO.:	REL: 1.0	REV:
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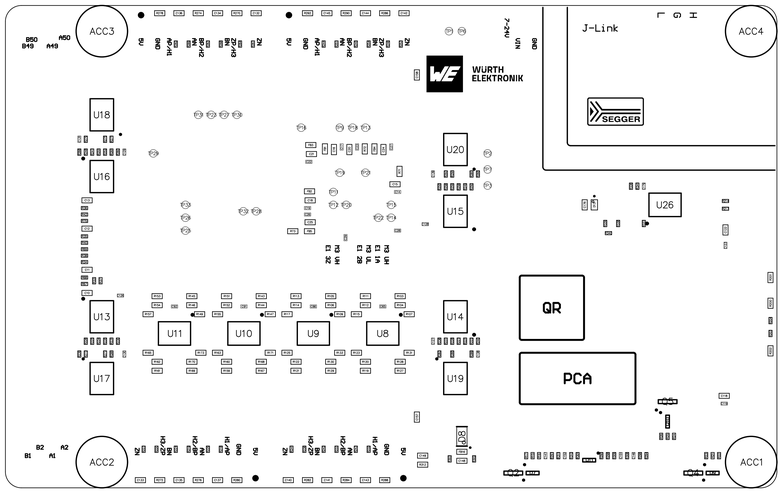


Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
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	Dielectric 4	PP-007	0,076mm	3.91	
	Dielectric 5	PP-007	0,076mm	3.91	
6	L6_INT5_SIG	CF-003	0,018mm		
	Core 3	Core-029	0,305mm	4.6	
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	Dielectric 6	PP-016	0,117mm	4.16	
8	L8_BOT_SIG	CF-004	0,035mm		
	Bottom Surface Finish	Nickel, Gold	0,004mm		
	Bottom Solder	Lack	0,030mm	3.8	
	Bottom Overlay				

Infineon Technologies AG
IFAG CSS ICW MCU APP IND
Am Campeon 1-12
85579 NEUBIBERG – GERMANY

ENGINEER:		TITLE: KIT_PSC3Mx_CC2	
PCB DESIGNER: M.N.			
DATE: 28.08.2026	PART NO.:	REL: 1.0	REV:
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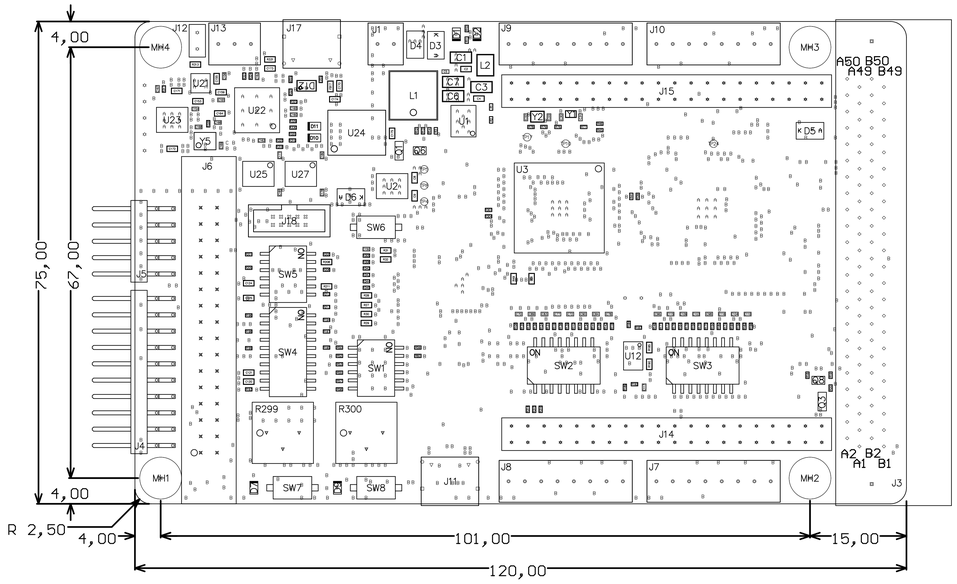


Infineon Technologies AG IFAG CSS ICW MCU APP IND Am Campeon 1–12 85579 NEUBIBERG – GERMANY	ENGINEER:	TITLE: KIT_PSC3Mx_CC2	
	PCB DESIGNER: M.N.		
	DATE: 28.08.2026	PART NO.:	REL: 1.0 / REV:
	SVN REVISION: Not in version control	FILE NAME: KIT_PSC3Mx_CC2.PcbDoc	APRV: <Appr.> / SCALE: 1:1

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Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad	Pad Shape	Template	Description	Hole Tolerance (+)	Hole Tolerance (-)	Hole Length	Routed Path Length
C	1	0,200mm (7,87mil)	PTH	Round	L1_TOP_SIG - L8_BOT_SIG	Via	Rounded	v45h20m0mx0				-	-
⌖	1	3,200mm (125,98mil)	NPTH	Round	L1_TOP_SIG - L8_BOT_SIG	Pad	Rounded	c320hn320				-	-
⧈	2	2,400mm (94,49mil)	PTH	Round	L1_TOP_SIG - L8_BOT_SIG	Pad	Rounded	c360h240				-	-
⌘	3	3,200mm (125,98mil)	PTH	Round	L1_TOP_SIG - L8_BOT_SIG	Pad	Rounded	c650h320				-	-
□	4	0,600mm (23,62mil)	PTH	Slot	L1_TOP_SIG - L8_BOT_SIG	Pad	Rounded	r180_100h60_140r100				1,400mm (55,12mil)	0,800mm (31,50mil)
○	4	0,600mm (23,62mil)	PTH	Slot	L1_TOP_SIG - L8_BOT_SIG	Pad	Rounded	r210_100h60_170r100				1,700mm (66,93mil)	1,100mm (43,31mil)
▽	4	0,650mm (25,59mil)	NPTH	Round	L1_TOP_SIG - L8_BOT_SIG	Pad	Rounded	c65hn65				-	-
▼	6	0,760mm (29,92mil)	PTH	Round	L1_TOP_SIG - L8_BOT_SIG	Pad	(Mixed)	(Mixed)				-	-
⊠	10	0,700mm (27,56mil)	PTH	Round	L1_TOP_SIG - L8_BOT_SIG	Pad	Rounded	c100h70				-	-
✖	32	1,000mm (39,37mil)	PTH	Round	L1_TOP_SIG - L8_BOT_SIG	Pad	(Mixed)	(Mixed)		0,100mm (3,94mil)	0,100mm (3,94mil)	-	-
◎	37	1,300mm (51,18mil)	PTH	Round	L1_TOP_SIG - L8_BOT_SIG	Pad	(Mixed)	(Mixed)				-	-
☼	39	1,100mm (43,31mil)	PTH	Round	L1_TOP_SIG - L8_BOT_SIG	Pad	(Mixed)	(Mixed)				-	-
✿	80	1,020mm (40,16mil)	PTH	Round	L1_TOP_SIG - L8_BOT_SIG	Pad	(Mixed)	(Mixed)				-	-
A	90	0,300mm (11,81mil)	PTH	Round	L1_TOP_SIG - L8_BOT_SIG	Via	Rounded	(Mixed)				-	-
◇	100	0,900mm (35,43mil)	PTH	Round	L1_TOP_SIG - L8_BOT_SIG	Pad	(Mixed)	(Mixed)				-	-
B	929	0,200mm (7,87mil)	PTH	Round	L1_TOP_SIG - L8_BOT_SIG	Via	Rounded	v45h20m0mx0				-	-
	1342 Total												

Slot definitions : **Routed Path Length** = Calculated from tool start centre position to tool end centre position.
Hole Length = Routed Path Length + Tool Size = Slot length as defined in the PCB layout



Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Lack	0,030mm	3.8	
	Top Surface Finish	Nickel, Gold	0,004mm		
1	L1_TOP_SIG	CF-004	0,035mm		
	Dielectric 1	PP-016	0,117mm	4.16	
2	L2_INT1_GND	CF-003	0,018mm		
	Core 1	Core-029	0,305mm	4.6	
3	L3_INT2_SIG	CF-003	0,018mm		
	Dielectric 2	PP-007	0,076mm	3.91	
	Dielectric 3	PP-007	0,076mm	3.91	
4	L4_INT3_PWR	CF-003	0,018mm		
	Core 2	Core-029	0,305mm	4.6	
5	L5_INT4_PWR	CF-003	0,018mm		
	Dielectric 4	PP-007	0,076mm	3.91	
	Dielectric 5	PP-007	0,076mm	3.91	
6	L6_INT5_SIG	CF-003	0,018mm		
	Core 3	Core-029	0,305mm	4.6	
7	L7_INT6_GND	CF-003	0,018mm		
	Dielectric 6	PP-016	0,117mm	4.16	
8	L8_BOT_SIG	CF-004	0,035mm		
	Bottom Surface Finish	Nickel, Gold	0,004mm		
	Bottom Solder	Lack	0,030mm	3.8	
	Bottom Overlay				

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ENGINEER:		TITLE: KIT_PSC3Mx_CC2	
PCB DESIGNER: M.N.			
DATE: 28.08.2026	PART NO.:	REL: 1.0	REV:
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